

## Logic level TOPFET SMD version of BUK117-50DL

BUK128-50DL

### DESCRIPTION

Monolithic temperature and overload protected logic level power MOSFET in **TOPFET2** technology assembled in a 3 pin surface mount plastic package.

### APPLICATIONS

General purpose switch for driving

- lamps
- motors
- solenoids
- heaters

in automotive systems and other applications.

### QUICK REFERENCE DATA

SYMBOL	PARAMETER	MAX.	UNIT
$V_{DS}$	Continuous drain source voltage	50	V
$I_D$	Continuous drain current	8	A
$P_D$	Total power dissipation	40	W
$T_j$	Continuous junction temperature	150	°C
$R_{DS(ON)}$	Drain-source on-state resistance	100	$m\Omega$
$I_{ISL}$	Input supply current $V_{IS} = 5$ V	650	$\mu A$

### FEATURES

- TrenchMOS output stage
- Current limiting
- Overload protection
- Overtemperature protection
- Protection latched reset by input
- 5 V logic compatible input level
- Control of output stage and supply of overload protection circuits derived from input
- Low operating input current permits direct drive by micro-controller
- ESD protection on all pins
- Ovvoltage clamping for turn off of inductive loads

### FUNCTIONAL BLOCK DIAGRAM

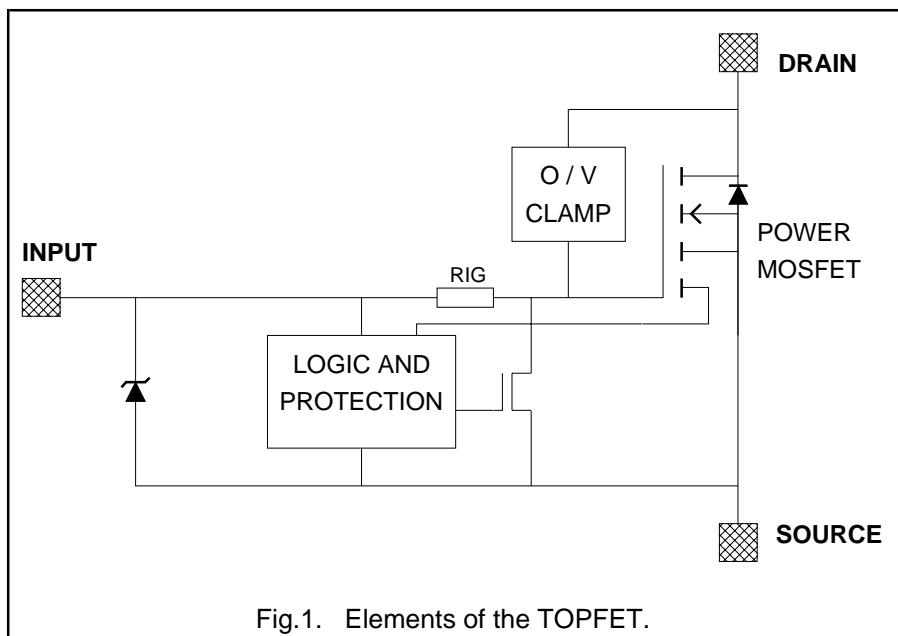
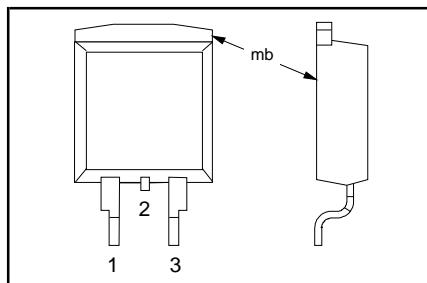


Fig.1. Elements of the TOPFET.

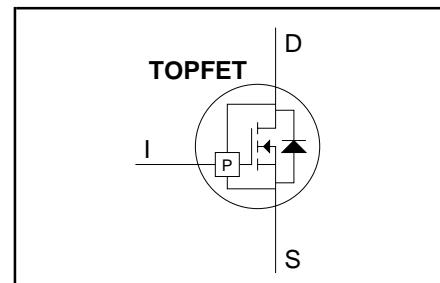
### PINNING - SOT404

PIN	DESCRIPTION
1	input
2	drain
3	source
mb	drain

### PIN CONFIGURATION



### SYMBOL



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### LIMITING VALUES

Limiting values in accordance with the Absolute Maximum Rating System (IEC 134)

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$V_{DS}$	Continuous drain source voltage <sup>1</sup>	-	-	50	V
$I_D$	Continuous drain current	$V_{IS} = 5 \text{ V}; T_{mb} = 25 \text{ }^\circ\text{C}$	-	self - limited	A
$I_D$	Continuous drain current	$V_{IS} = 5 \text{ V}; T_{mb} \leq 110 \text{ }^\circ\text{C}$	-	8	A
$I_I$	Continuous input current	-	-5	5	mA
$I_{IRM}$	Non-repetitive peak input current	$t_p \leq 1 \text{ ms}$	-10	10	mA
$P_D$	Total power dissipation	$T_{mb} \leq 25 \text{ }^\circ\text{C}$	-	40	W
$T_{stg}$	Storage temperature	-	-55	175	$^\circ\text{C}$
$T_j$	Continuous junction temperature <sup>2</sup>	normal operation	-	150	$^\circ\text{C}$
$T_{sold}$	Case temperature	during soldering	-	260	$^\circ\text{C}$

### ESD LIMITING VALUE

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$V_C$	Electrostatic discharge capacitor voltage	Human body model; $C = 250 \text{ pF}; R = 1.5 \text{ k}\Omega$	-	2	kV

### OVERVOLTAGE CLAMPING LIMITING VALUES

At a drain source voltage above 50 V the power MOSFET is actively turned on to clamp overvoltage transients.

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$E_{DSM}$	Inductive load turn-off	$I_{DM} = 8 \text{ A}; V_{DD} \leq 20 \text{ V}$	-	100	mJ
$E_{DRM}$	Non-repetitive clamping energy	$T_{mb} \leq 25 \text{ }^\circ\text{C}$	-	20	mJ
	Repetitive clamping energy	$T_{mb} \leq 95 \text{ }^\circ\text{C}; f = 250 \text{ Hz}$	-		

### OVERLOAD PROTECTION LIMITING VALUE

With an adequate protection supply provided via the input pin, TOPFET can protect itself from two types of overload - overtemperature and short circuit load.

SYMBOL	PARAMETER	REQUIRED CONDITION	MIN.	MAX.	UNIT
$V_{DS}$	Drain source voltage <sup>3</sup>	$4 \text{ V} \leq V_{IS} \leq 5.5 \text{ V}$	0	35	V

### THERMAL CHARACTERISTIC

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$R_{th,j-mb}$	Thermal resistance Junction to mounting base	-	-	2.5	3.1	K/W
$R_{th,j-a}$	Junction to ambient	minimum footprint FR4 PCB	-	50	-	K/W

<sup>1</sup> Prior to the onset of overvoltage clamping. For voltages above this value, safe operation is limited by the overvoltage clamping energy.

<sup>2</sup> A higher  $T_j$  is allowed as an overload condition but at the threshold  $T_{j(TO)}$  the over temperature trip operates to protect the switch.

<sup>3</sup> All control logic and protection functions are disabled during conduction of the source drain diode.

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**OUTPUT CHARACTERISTICS**
Limits are for  $-40^{\circ}\text{C} \leq T_{mb} \leq 150^{\circ}\text{C}$ ; typicals are for  $T_{mb} = 25^{\circ}\text{C}$  unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$V_{(CL)DSS}$	<b>Off-state</b> Drain-source clamping voltage	$V_{IS} = 0 \text{ V}$ $I_D = 10 \text{ mA}$	50	-	-	V
		$I_{DM} = 1 \text{ A}; t_p \leq 300 \mu\text{s}; \delta \leq 0.01$	50	60	70	V
$I_{DSS}$	Drain source leakage current	$V_{DS} = 40 \text{ V}$ $T_{mb} = 25^{\circ}\text{C}$	-	-	100	$\mu\text{A}$
			-	0.1	10	$\mu\text{A}$
$R_{DS(ON)}$	<b>On-state</b> Drain-source resistance	$I_{DM} = 3 \text{ A}; t_p \leq 300 \mu\text{s}; \delta \leq 0.01$ $V_{IS} \geq 4.4 \text{ V}$ $T_{mb} = 25^{\circ}\text{C}$	-	-	190	$\text{m}\Omega$
		$V_{IS} \geq 4 \text{ V}$ $T_{mb} = 25^{\circ}\text{C}$	-	68	100	$\text{m}\Omega$
			-	-	200	$\text{m}\Omega$
			-	72	105	$\text{m}\Omega$

**OVERLOAD CHARACTERISTICS**
 $-40^{\circ}\text{C} \leq T_{mb} \leq 150^{\circ}\text{C}$  unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$I_D$	<b>Short circuit load</b> Drain current limiting	$V_{DS} = 13 \text{ V}$ $V_{IS} = 5 \text{ V};$ $4.4 \text{ V} \leq V_{IS} \leq 5.5 \text{ V}$ $4 \text{ V} \leq V_{IS} \leq 5.5 \text{ V}$	8	12	16	A
			6	-	18	A
		$T_{mb} = 25^{\circ}\text{C}$	5	-	18	A
$P_{D(TO)}$ $T_{DSC}$	<b>Overload protection</b> Overload power threshold Characteristic time	$V_{IS} = 5 \text{ V};$ $T_{mb} = 25^{\circ}\text{C}$ device trips if $P_D > P_{D(TO)}$ which determines trip time <sup>1</sup>	20	55	80	W
			200	350	600	$\mu\text{s}$
$T_{j(TO)}$	<b>Overtemperature protection</b> Threshold junction temperature <sup>2</sup>		150	170	-	$^{\circ}\text{C}$

<sup>1</sup> Trip time  $t_{dsc}$  varies with overload dissipation  $P_D$  according to the formula  $t_{dsc} \approx T_{DSC} / \ln[ P_D / P_{D(TO)} ]$ .<sup>2</sup> This is independent of the dV/dt of input voltage  $V_{IS}$ .

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**INPUT CHARACTERISTICS**

The supply for the logic and overload protection is taken from the input.

Limits are for  $-40^{\circ}\text{C} \leq T_{mb} \leq 150^{\circ}\text{C}$ ; typicals are for  $T_{mb} = 25^{\circ}\text{C}$  unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$V_{IS(TO)}$	Input threshold voltage	$V_{DS} = 5 \text{ V}$ ; $I_D = 1 \text{ mA}$ $T_{mb} = 25^{\circ}\text{C}$	0.6 1.1	- 1.6	2.4 2.1	V
$I_{IS}$	Input supply current	normal operation; $V_{IS} = 5 \text{ V}$ $V_{IS} = 4 \text{ V}$	100 80	220 195	400 330	$\mu\text{A}$
$I_{ISL}$	Input supply current	protection latched; $V_{IS} = 5 \text{ V}$ $V_{IS} = 3 \text{ V}$	200 130	400 250	650 430	$\mu\text{A}$
$V_{ISR}$	Protection reset voltage <sup>1</sup>	reset time $t_r \geq 100 \mu\text{s}$	1.5	2	2.9	V
$t_r$	Latch reset time	$V_{IS1} = 5 \text{ V}$ , $V_{IS2} < 1 \text{ V}$	10	40	100	$\mu\text{s}$
$V_{(CL)IS}$	Input clamping voltage	$I_I = 1.5 \text{ mA}$	5.5	-	8.5	V
$R_{IG}$	Input series resistance <sup>2</sup> to gate of power MOSFET	$T_{mb} = 25^{\circ}\text{C}$	-	33	-	k $\Omega$

**SWITCHING CHARACTERISTICS**

$T_{mb} = 25^{\circ}\text{C}$ ;  $V_{DD} = 13 \text{ V}$ ; resistive load  $R_L = 4 \Omega$ . Refer to waveform figure and test circuit.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$t_{d\ on}$	Turn-on delay time	$V_{IS} = 5 \text{ V}$	-	8	20	$\mu\text{s}$
$t_r$	Rise time		-	20	50	$\mu\text{s}$
$t_{d\ off}$	Turn-off delay time	$V_{IS} = 0 \text{ V}$	-	25	70	$\mu\text{s}$
$t_f$	Fall time		-	16	40	$\mu\text{s}$

<sup>1</sup> The input voltage below which the overload protection circuits will be reset.

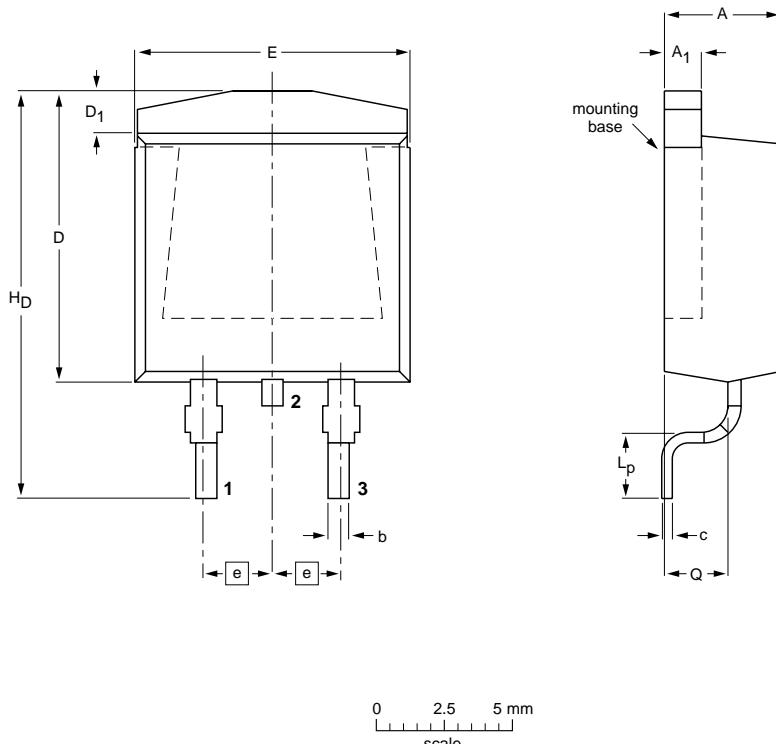
<sup>2</sup> Not directly measurable from device terminals.

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**MECHANICAL DATA**
**Plastic single-ended surface mounted package (Philips version of D<sup>2</sup>-PAK); 3 leads  
(one lead cropped)**

SOT404

**DIMENSIONS (mm are the original dimensions)**

UNIT	A	A <sub>1</sub>	b	c	D <sub>max.</sub>	D <sub>1</sub>	E	e	L <sub>p</sub>	H <sub>D</sub>	Q
mm	4.50 4.10	1.40 1.27	0.85 0.60	0.64 0.46	11	1.60 1.20	10.30 9.70	2.54	2.90 2.10	15.40 14.80	2.60 2.20

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT404						98-12-14 99-06-25

*Fig.2. SOT404 surface mounting package<sup>1</sup>, centre pin connected to mounting base.*

<sup>1</sup> Epoxy meets UL94 V0 at 1/8". Net mass: 1.4 g.  
For soldering guidelines and SMD footprint design, please refer to Data Handbook SC18.

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**DEFINITIONS**

<b>DATA SHEET STATUS</b>		
<b>DATA SHEET STATUS<sup>1</sup></b>	<b>PRODUCT STATUS<sup>2</sup></b>	<b>DEFINITIONS</b>
Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice
Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product
Product data	Production	This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Changes will be communicated according to the Customer Product/Process Change Notification (CPCN) procedure SNW-SQ-650A
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<b>Application information</b>		
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